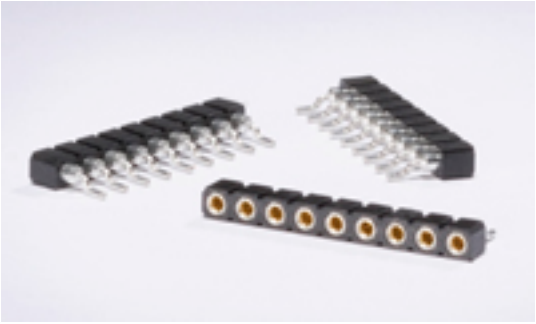
.050” SMT Sockets and Headers Suit Low Profile IO Apps



Mill-Max offers a choice between .050” (1.270 mm) and .100” (2.540 mm) grid horizontal Z-Bend sockets and receptacles. For low profile IO applications, these SMT SIP socket and header strips are assembled parallel to their board surface. They are appropriate for placement near the board edge for easy access test connections and creating pluggable adapter modules which can sit perpendicular to the motherboard (mated to a vertical connector,) effectively conserving precious board real estate. The 310, .100” (2,540 mm) grid, horizontal Surface Mount Z-Bend Sockets use MM #1023 receptacles that accept pin diameters from .015” to .025” (0.381 to 0.635 mm.) These sockets are rated 3 A per position. Series 801, .100” (2.540 mm) grid, uses MM #1303 receptacles that accept pin diameters from .025” - .037” (0.635 – 0.940 mm) and .025” (0,635 mm) square leads. These sockets are rated at 4.5 A per pin position. Series 850, .050” (1.270 mm) grid horizontal SMT Z-Bend Headers are available with .016” (0.406 mm) diameter solder tails and pluggable pins, using MM #4006-1 receptacles. Series 851 horizontal SMT Z-Bend sockets use MM #4890-1 receptacles that accept pin diameters from .015” - .020” (0.381 mm – 0.508 mm.) These headers are rated at 3 amps per pin position. Standard configurations are 2-20 positions with a .005 (0,127 mm) coplanarity rating.

Mill-Max
516-922-6000, www.mill-max.com [1]

Source URL (retrieved on *07/29/2014 - 4:41am*):
http://www.ecnmag.com/products/2010/04/050%E2%80%9D-smt-sockets-and-headers-suit-low-profile-io-apps

Links:
[1] http://www.mill-max.com